

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|---|---|------------------|---------|------------------|
| L1 | 55 | (carrier ((circuit printed wiring) near1 board)) same (chip die (semiconductor near (device element))) same (flipchip (flip near chip)) same (heat near (spreader spread plate dissipating sink)) same (encapsulant sealing)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/02/01 16:39 |
| L2 | 1 | 1 same (standoff (stand adj off) spacer) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/02/01 16:38 |
| L3 | 4010 | 257/706,707,717,720,796.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/02/01 16:37 |
| L4 | 2078 | 438/122,123.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/02/01 16:38 |
| L5 | 5865 | 3 4 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/02/01 16:38 |
| L6 | 0 | 5 same (standoff (stand adj off) spacer) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/02/01 16:39 |
| L7 | 481 | 5 and (standoff (stand adj off) spacer) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/02/01 16:39 |
| L8 | 126 | 7 and (carrier ((circuit printed wiring) near1 board)) and (chip die (semiconductor near (device element))) and (flipchip (solder adj (bump ball)) (flip near chip)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/02/01 16:40 |

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|----|-----|---------|---|----|----|------------------|
| L9 | 123 | 8 not 1 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/02/01 16:40 |
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